



(12) **United States Design Patent**  
**Furutani**

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(45) **Date of Patent:** **\*\* Jun. 30, 2020**

- (54) **SEMICONDUCTOR MODULE**
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- (\*\*) Term: **15 Years**
- (21) Appl. No.: **29/673,185**
- (22) Filed: **Dec. 12, 2018**

H05K 1/141; H05K 1/142; H05K 1/144;  
H05K 1/18; H05K 1/181; H05K 1/182;  
H05K 1/026  
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and right side perspective view of a first embodiment of a semiconductor module showing my new design;  
FIG. 2 is a rear, bottom, and left side perspective view thereof;  
FIG. 3 is a front view thereof;  
FIG. 4 is a rear view thereof;  
FIG. 5 is a top plan view thereof;  
FIG. 6 is a bottom plan view thereof;  
FIG. 7 is a right side view thereof, the left side view being a mirror image of FIG. 7; and,  
FIG. 8 is a cross sectional view taken along line 8-8 in FIG. 5.

**1 Claim, 6 Drawing Sheets**

(30) **Foreign Application Priority Data**

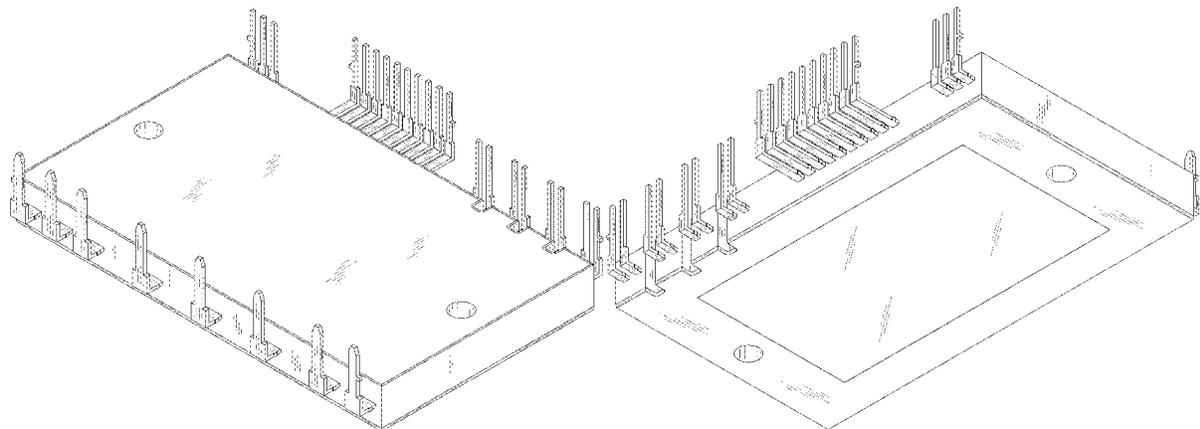
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(51) **LOC (12) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

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438/15, 25, 26, 51, 55, 63, 64, 106
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H01L 2021/00; H01L 2021/02; H01L  
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H02B 6/4201; G02B 6/4256; G02B  
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G02B 6/428; G02B 6/4281; H05K 1/14;



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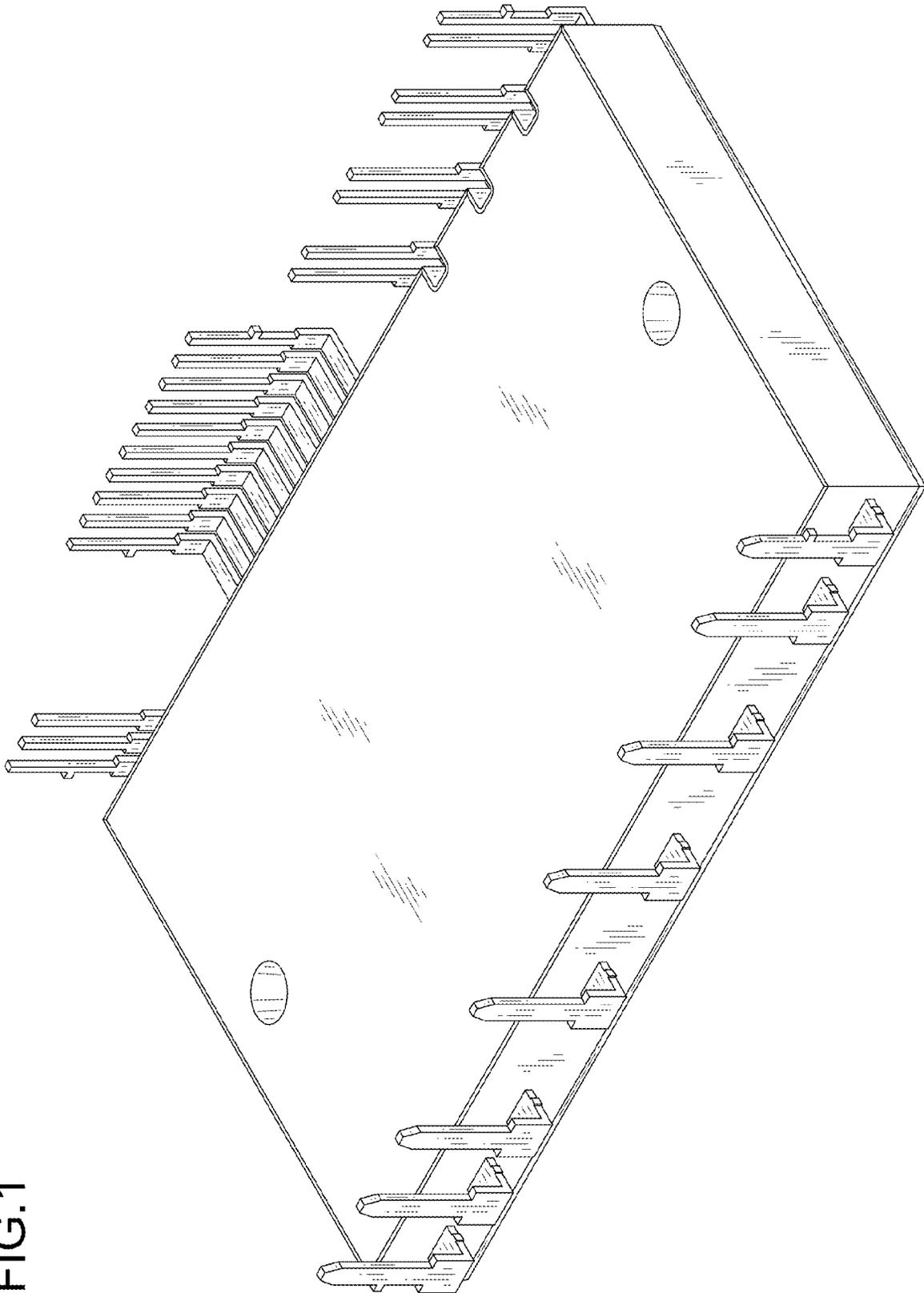


FIG.1

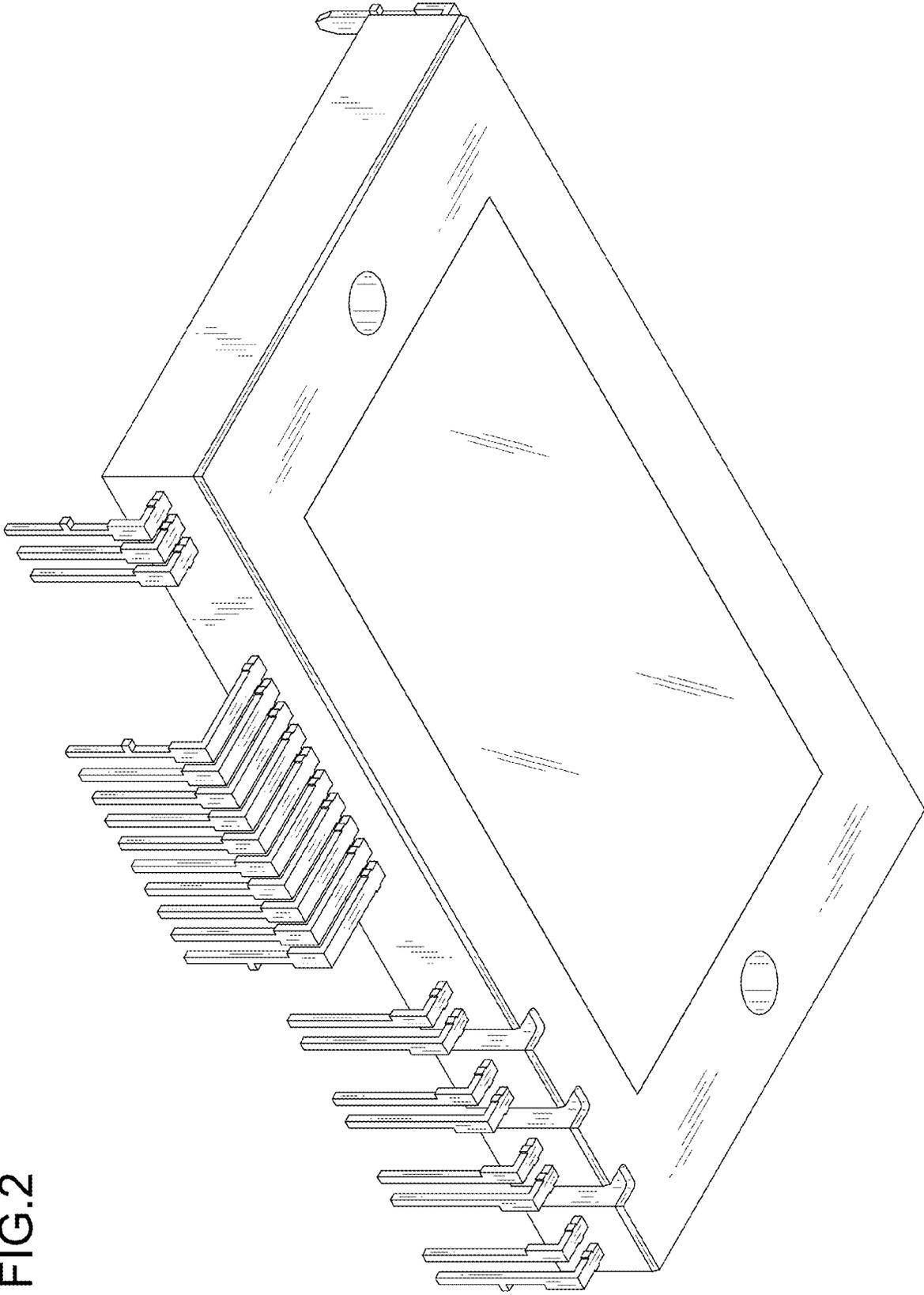


FIG.2

FIG.3

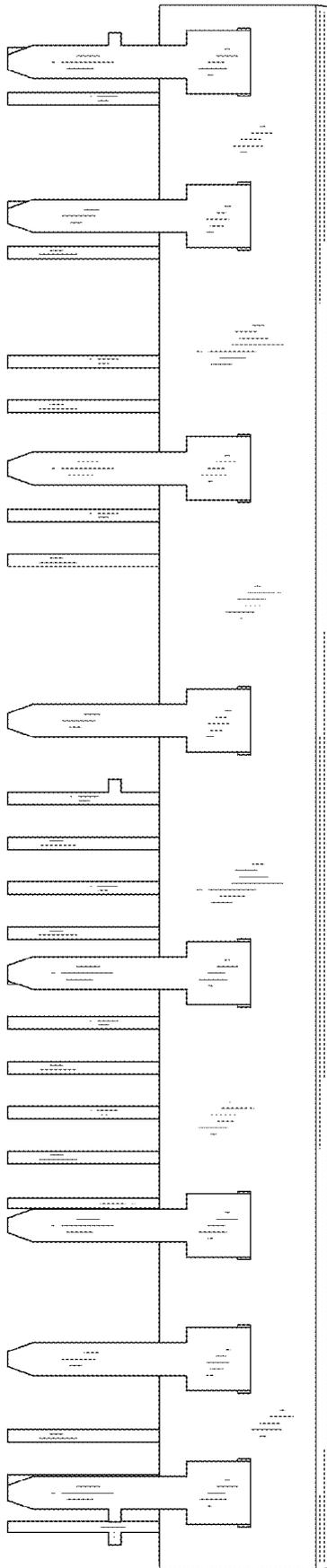


FIG.4

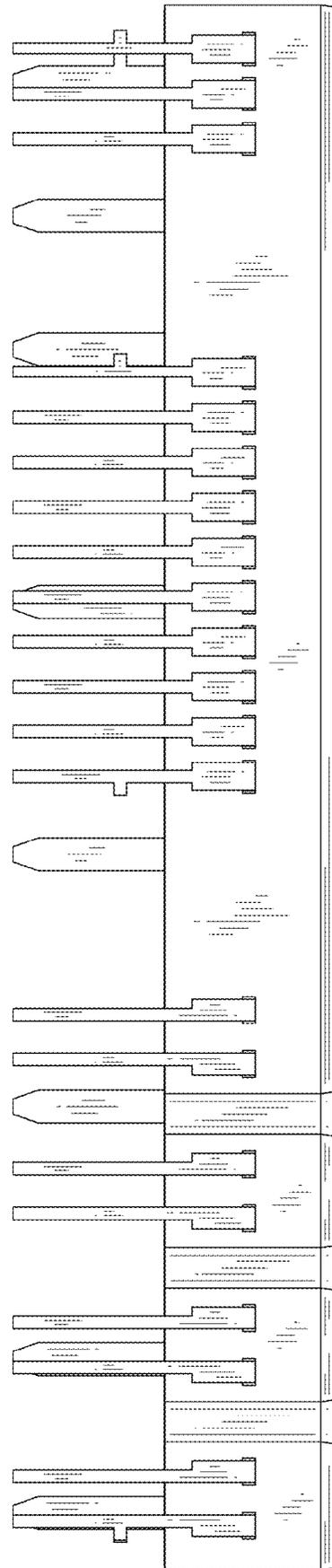


FIG. 5

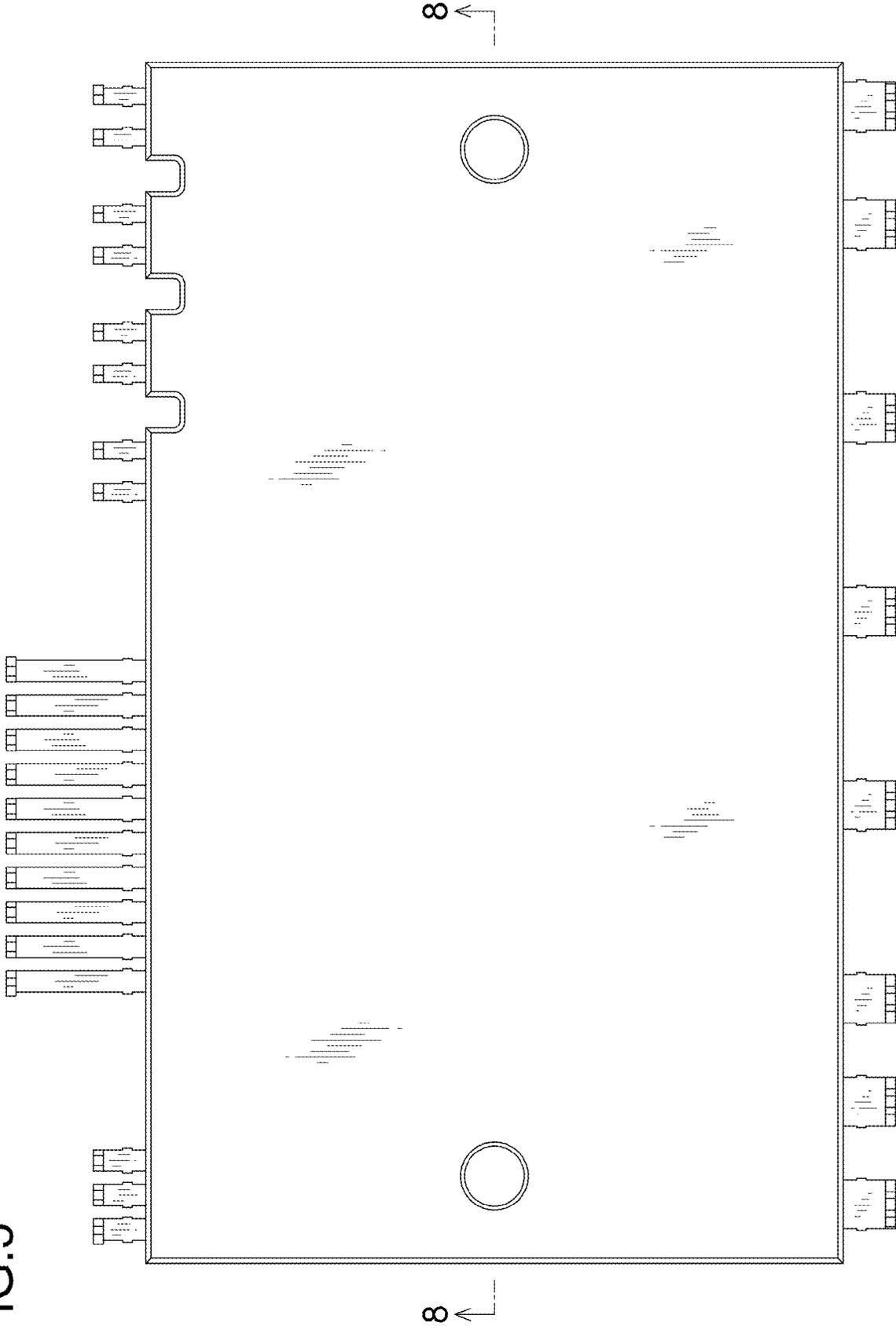


FIG. 6

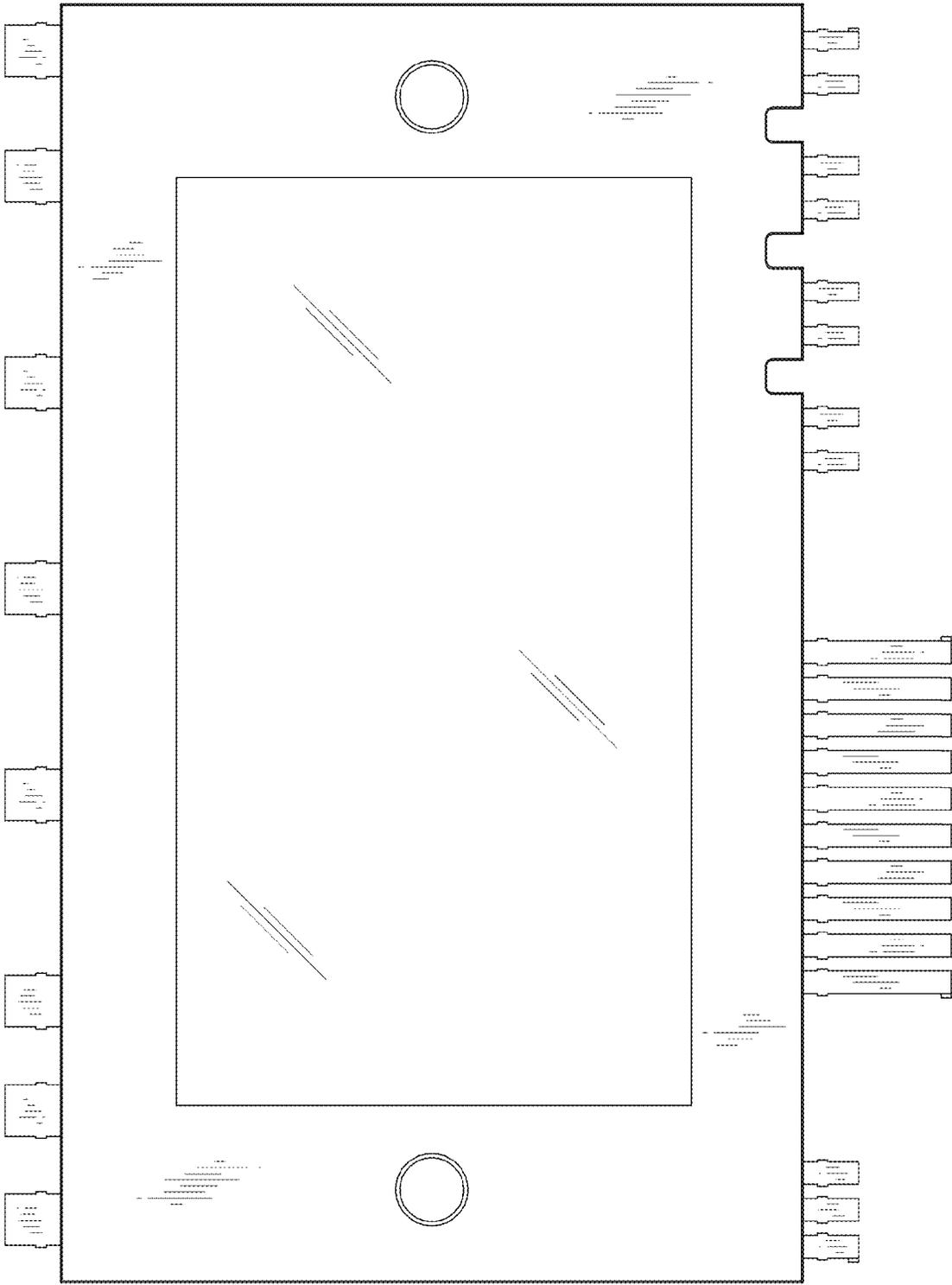


FIG.7

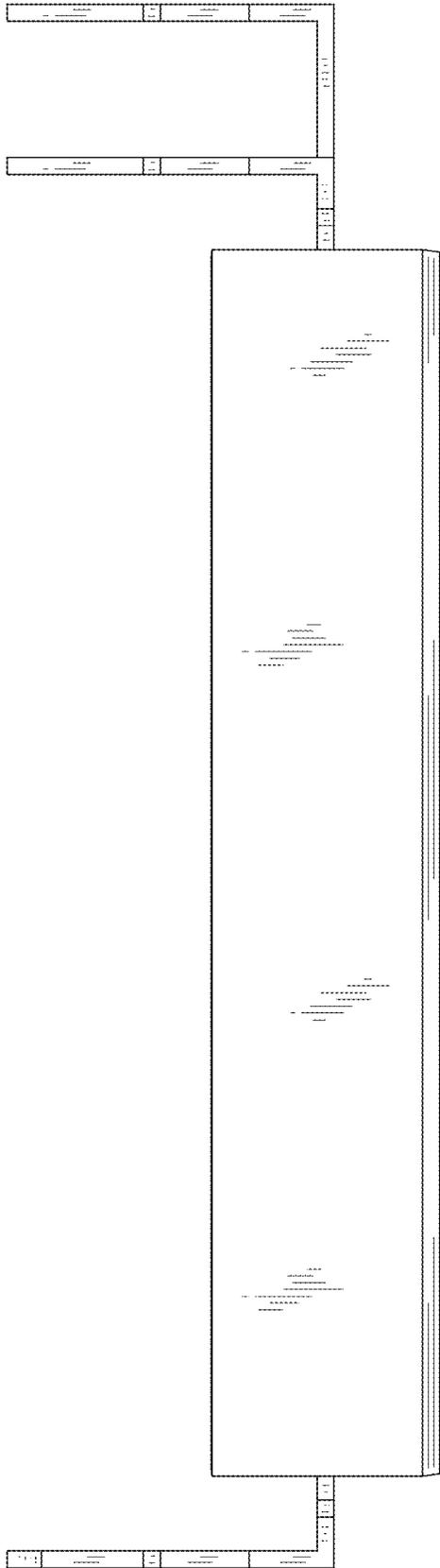


FIG.8

